

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S53	36	S50 and (semiconductor wafer substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/10 09:58
S52	3	S50 and "257".clas.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/10 09:58
S51	0	S50 and "438".clas.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/10 09:57
S50	48	S49 with S45 with S46 with S47	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/10 09:57
S49	28041	"peel strength" "adhesive strength"	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/10 09:57
S44	11784	"peel strength"	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/10 09:56
S48	15	S44 with S45 with S46 with S47	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/10 08:46
S47	487945	tape	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/10 08:45
S46	2909204	pressure	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/10 08:45
S45	2565901	temperature	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/10 08:45
S43	27	S42 and semiconductor	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/05 11:54
S42	135	(adhesive tape) with N/m	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/05 11:54
S41	48	S40 and semiconductor	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/05 11:54
S40	295	(adhesive tape) with N/m	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/05 11:54

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S39	3	(adhesive tape) with peel with strength	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/05 11:42
S34	1	("20060043607").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/05/05 11:40
S38	1	("WF-55-X4-HT")	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/04 15:42
S37	1	("WF-55-X4-HT") with (tape)	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/04 15:42
S36	342	S35 and (adhesive tape) with (strength peel\$4 force)	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/04 15:41
S35	1736	(438/118).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/05/04 15:19

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S3	855	("438/for.227").CCLS.	EPO; JPO; DERWENT	OR	OFF	2005/12/07 16:56
S5	105811	"438"/\$.ccls.	US-PGPUB; USPAT	OR	OFF	2006/03/24 10:36
S6	196566	"257"/\$.ccls.	US-PGPUB; USPAT	OR	OFF	2006/03/24 10:36
S7	746088	semiconductor or ic or "integrated circuit" or microelectronic	US-PGPUB; USPAT	OR	OFF	2006/03/24 10:36
S8	771582	S5 or S6 or S7	US-PGPUB; USPAT	OR	OFF	2006/04/12 11:51
S9	221599	S5 or S6	US-PGPUB; USPAT	OR	OFF	2006/04/12 11:50
S10	10742	"peel strength"	US-PGPUB; USPAT	OR	OFF	2007/05/09 12:46
S11	1912772	temperature	US-PGPUB; USPAT	OR	OFF	2007/05/09 12:46
S12	1971722	pressure	US-PGPUB; USPAT	OR	OFF	2007/05/09 12:46
S13	168	S10 with S11 with S12	US-PGPUB; USPAT	OR	OFF	2007/05/09 12:47
S14	122980	"438"/\$.ccls.	US-PGPUB; USPAT	OR	OFF	2007/05/09 12:48
S15	237971	"257"/\$.ccls.	US-PGPUB; USPAT	OR	OFF	2007/05/09 12:48
S16	877399	semiconductor or ic or "integrated circuit" or microelectronic	US-PGPUB; USPAT	OR	OFF	2007/05/09 12:49
S17	907443	S14 or S15 or S16	US-PGPUB; USPAT	OR	OFF	2007/05/09 12:49
S18	19	S13 and S16	US-PGPUB; USPAT	OR	OFF	2007/05/09 13:11
S19	1344	low with S10	US-PGPUB; USPAT	OR	OFF	2007/05/09 13:11
S20	225	S16 and S19	US-PGPUB; USPAT	OR	OFF	2007/05/09 13:11
S21	220	S20 not S18	US-PGPUB; USPAT	OR	OFF	2007/05/09 13:12
S22	856	low near3 S10	US-PGPUB; USPAT	OR	OFF	2007/05/09 13:13
S23	119	S16 and S22	US-PGPUB; USPAT	OR	OFF	2007/05/09 13:13
S24	118	S23 not S18	US-PGPUB; USPAT	OR	OFF	2007/05/09 13:13